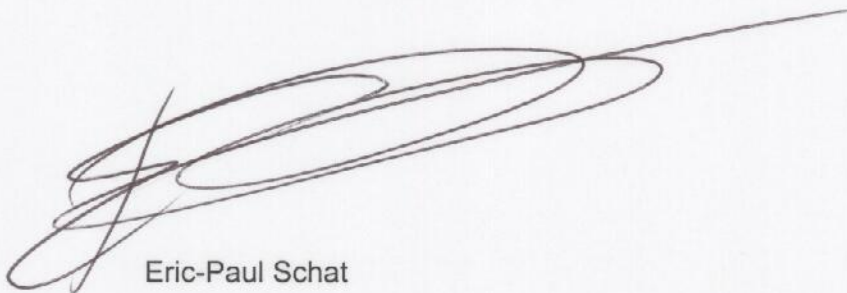


1 October 2006

CERTIFICATE OF COMPLIANCE - RoHS Declaration

NXP Semiconductors certifies that to its knowledge semiconductor products designated to be "Pb-free" conform to the requirements of the European Union's Restriction on Use of Hazardous Substances in Electrical and Electronic Equipment (RoHS) Directive 2002/95/EC. Lead (Pb) is the last of the RoHS Substances to be removed since the other restricted substances were already not used in NXP Semiconductors' products.

NXP's terms "Lead-free" or "Pb-free" mean semiconductor products that are compatible with the current RoHS requirements for all six of the RoHS Substances (see NXP's lists of restricted and relevant substances), including the requirement that Lead (Pb) not exceed 1000 PPM by weight, in all homogenous subcomponent materials. Where designed to be soldered at high temperatures, NXP Pb-free products are suitable for use in specified Pb-free processes. This status is based on NXP's understanding of RoHS and NXP's knowledge of the materials that go into its products as of the date of disclosure of information.



Eric-Paul Schat
Senior Director, Sustainability Office
NXP Semiconductors